BCC Resins HPX-850

Epoxy; Epoxide

BCC Products Inc.

Message:

HPX-850 is a light weight, heat resistant, two component epoxy backfill system. Like BC 7020, the filler portion is pre-blended into the resin and hardener components for easier handling, thus simplifying the mixing process. HPX-850 features advantages such as low cost, long pot life, machineability, and low shrinkage. It is ideally suited for numerous applications involving mold and core constructions.
HPX-850 can be removed from the mold after allowing to set 24 hours @ room temperature (75°F). Post cure for applications requiring temperatures above 150°F can be accomplished in an oven or in use by a gradual heat rise; 2 hours @ 150°F, plus 2 hours @ 250°F, plus 2 hours at 300°F.

General Information	
Features	High Heat Resistance Low Shrinkage Machinable
Uses	Molds/Dies/Tools
Appearance	Grey
Forms	Paste
Processing Method	Casting

Physical	Nominal Value	Unit	Test Method
Specific Gravity			
--	0.818	g/cm³	ASTM D792
--	0.830	g/cm³	ASTM D1505
Molding Shrinkage - Flow	0.020	%	ASTM D955

Thermal	Nominal Value	Unit	Test Method
Deflection Temperature Under Load (1.8 MPa, Unannealed)	141	°C	ASTM D648

Thermoset	Nominal Value	Unit
Thermoset Components		
Hardener	Mix Ratio by Weight: 1.0	
Resin	Mix Ratio by Weight: 6.0	
Pot Life (24°C)	120 to 150	min
Demold Time	1400	min

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